



ON-TECP Product Data Sheet

Thermally and Electrically Conductive Paste

DESCRIPTION

ON-TECP is silver-filled silicone compound used to fill minor imperfections between surfaces. ON-TECP has excellent thermal properties combined with its low vapor pressure makes it ideal for sputtering target to cathode body contact as well as any thermal transfer process.

TYPICAL PROPERTIES	
Operating Range	-55° - 200° C
Volume Resistivity	0.01 ohm cm
Thermal Conductivity	0.57 W/m-K
Density	3.5g/cc
Vapor Pressure	2 x 10 ⁹ TORR
Shelf Life	1 year

APPLICATION

With the sputtering target side which will be in contact with the cooling plate, apply a small amount of the mixed compound. A thin layer of approximately 0.015" thick is adequate, do not over apply the compound. Install the target making sure that there is firm contact between the cooling plate and target. Clean up any excess.

State of the epoxy as shipped is highly electrically and conductive. Paste may be cut to thin out by using commercially available high vacuum grease such as Dow Corning High Vacuum Grease.

WARNING: THIS MATERIAL IS SOLD FOR INDUSTRIAL USE ONLY

Uncured epoxy adhesives - consisting of resin and hardener components - may cause dermatitis, skin sensitization or other allergic responses. Prevent all contact with skin and eyes. If contact occurs, flush immediately with plenty of water (get prompt medical attention for eyes). Keep away from heat and open flames. KEEP OUT OF REACH OF CHILDREN. Immediately clean up any spills that may occur.

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